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Predictive modeling for presumptive diagnosis of type 2 diabetes mellitus based on symptomatic analysis (Conference Paper)

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Abstract [View references \(19\)](#)

The purpose of using Predictive Modeling for presumptive diagnosis of Type 2 Diabetes Mellitus based on symptomatic analysis is the optimization of the diagnosis phase of the disease through the process of evaluating symptomatic characteristics and daily habits, allowing the forecasting of T2DM without the need of medical exams through predictive analysis. The tool used was SAP Predictive Analytics and in order to identify the most suitable algorithm for the prediction, we evaluated them based on precision and false positive/negative relations, having found the Auto Classification algorithm as the most accurate with a 91.7% precision and a better correlation between false positives (8) and false negatives (3). © 2017 IEEE.

Author keywords

- Auto Classification algorithm

- diabetes mellitus
- predictive analytics

Indexed keywords

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